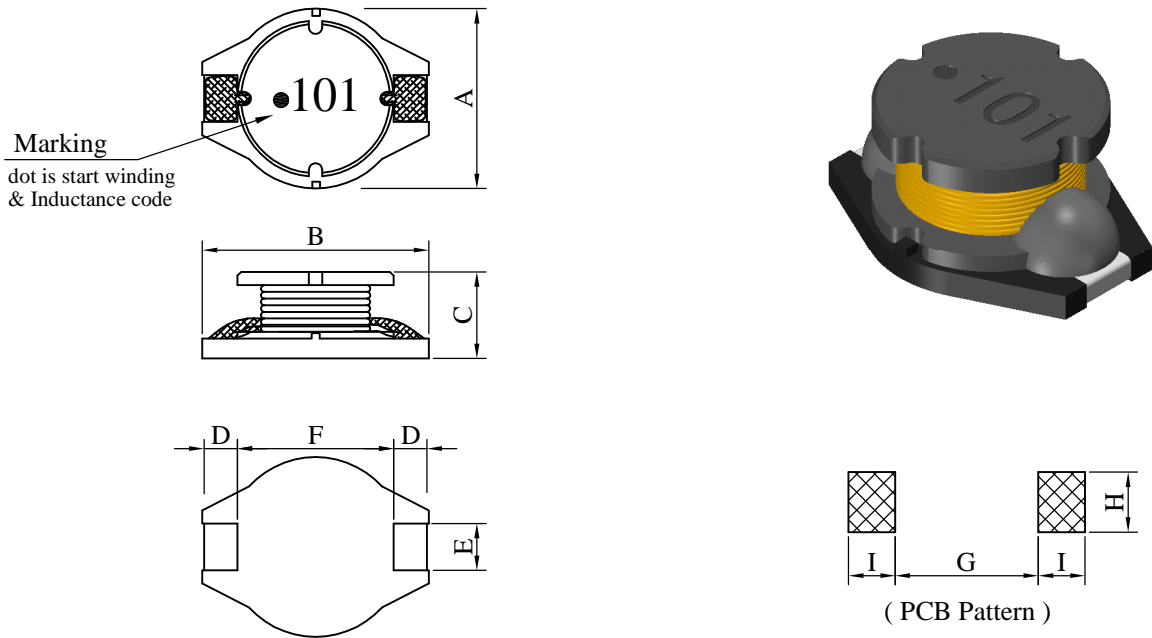


SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	SMD Power Inductor	ABC'S DWG NO.	SB0805□□□□F□-□□□		
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I . Configuration and dimensions :



Unit : m/m

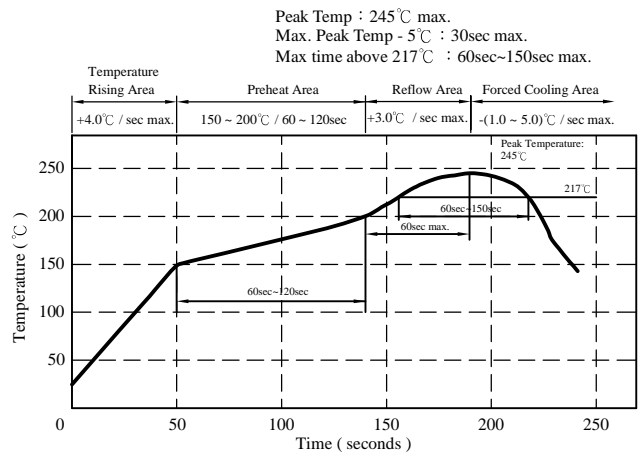
A	B	C	D	E	F	G	H	I
8.00 ±0.3	10.50 ±0.3	5.00 ±0.3	2.10 ±0.2	2.00 ±0.2	6.00 ±0.3	5.70 ref.	2.20 ref.	2.40 ref.

II . Description :

- a . Ferrite drum core construction.
- b . Enamelled copper wire : F class
- c . Product weight : 0.80g (ref.)
- d . Moisture sensitivity Level 1
- e . Products comply with RoHS' requirements
- f . Halogen free available.

III . General specification :

- a . Storage temp. : -40°C ----+125°C
- b . Operating temp. : -40°C ----+125°C
(Temp. rise included)
- c . Resistance to solder heat : 245°C .10 secs.



SPECIFICATION FOR APPROVAL

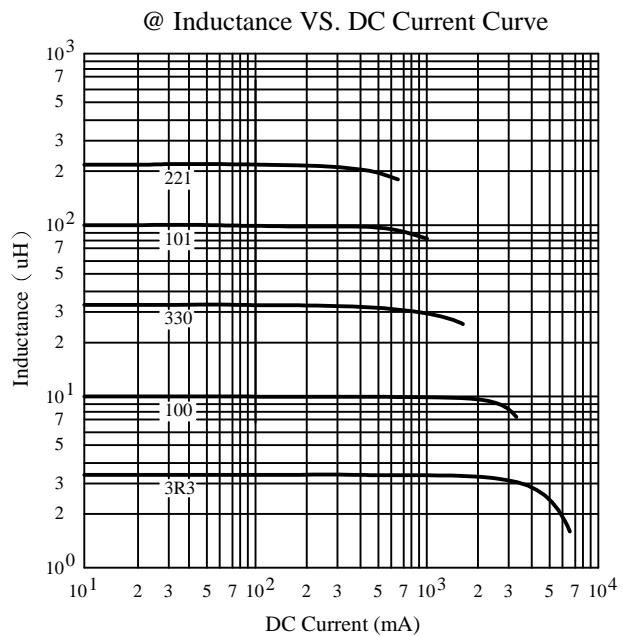
REF. :

PROD. NAME	SMD Power Inductor	ABC'S DWG NO.	SB0805□□□□F□-□□□		
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IV . Electrical characteristics :

DWG. No.	Inductance (uH) 0.1 V / 100 kHz	RDC (Ω) max.	Irms (A) max.	Isat (A) typ.
SB08053R3MF□-□□□	3.3±20%	0.022	5.00	5.20
SB08054R7MF□-□□□	4.7±20%	0.028	4.20	4.00
SB08056R8MF□-□□□	6.8±20%	0.040	3.40	3.40
SB0805100MF□-□□□	10.0±20%	0.050	3.00	2.80
SB0805150MF□-□□□	15.0±20%	0.070	2.40	2.30
SB0805220MF□-□□□	22.0±20%	0.100	2.00	1.85
SB0805330MF□-□□□	33.0±20%	0.145	1.72	1.54
SB0805470YF□-□□□	47.0±15%	0.200	1.40	1.28
SB0805680YF□-□□□	68.0±15%	0.270	1.20	1.15
SB0805101YF□-□□□	100.0±15%	0.400	1.00	0.92
SB0805151YF□-□□□	150.0±15%	0.560	0.75	0.75
SB0805221YF□-□□□	220.0±15%	0.860	0.62	0.62
SB0805331YF□-□□□	330.0±15%	1.500	0.46	0.50

- 1). □ : Packaging information : □ Code
- 2). "-□□□" : Reference code
- 3). Electrical specifications at 25°C
- 4). Irms base on Temp. rise 40°C max.
- 5). Isat base on $\Delta L / L0A=10\%$ typ.



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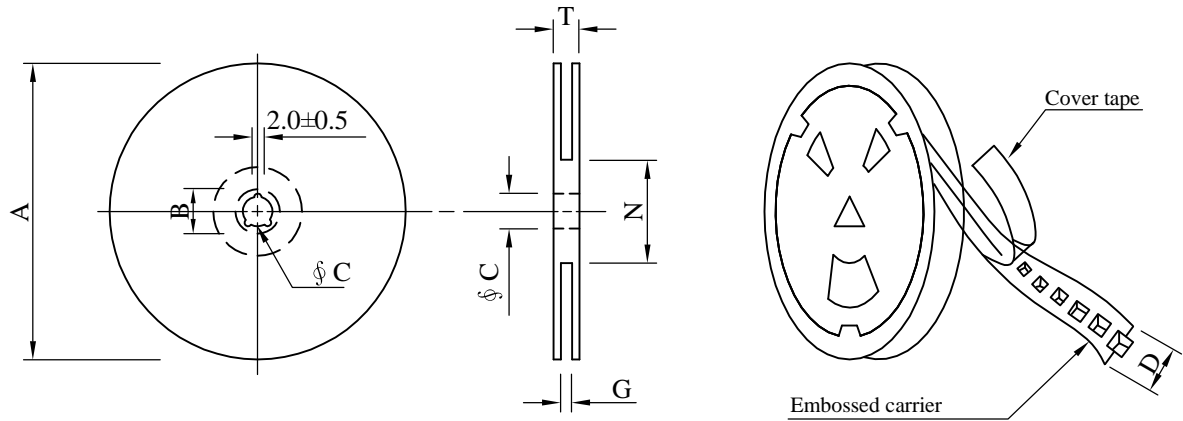
SPECIFICATION FOR APPROVAL

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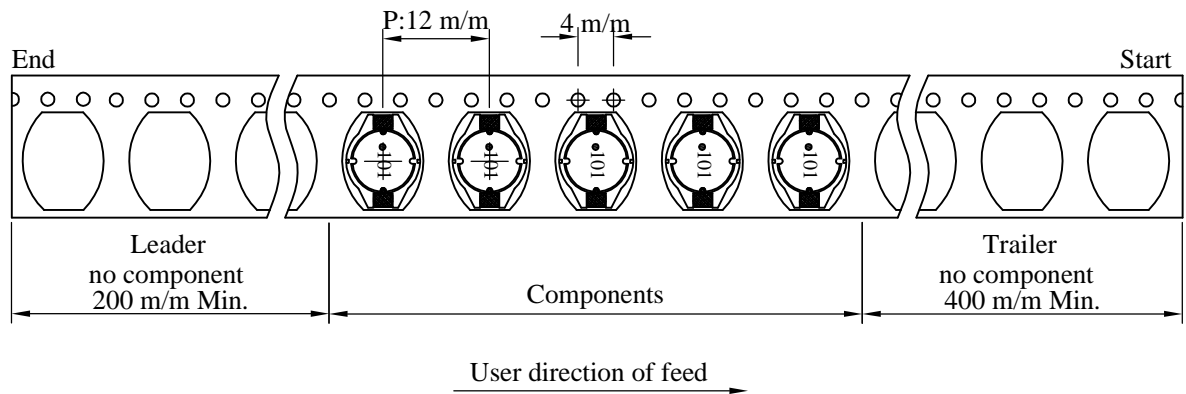
PROD. NAME	SMD Power Inductor	ABC'S DWG NO.	SB0805□□□□F□-□□□		
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V . Packaging information :

(1) Configuration :



※Carrier tape width : D



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
13 - 24	330	21±0.8	13±0.5	24	26 ⁺⁰	60 ⁻⁰	30.4

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (pcs)	G.W. (Kg)	Size (cm)
B	800	1160	13 - 24	3,200	5.9	38 x 37 x 22

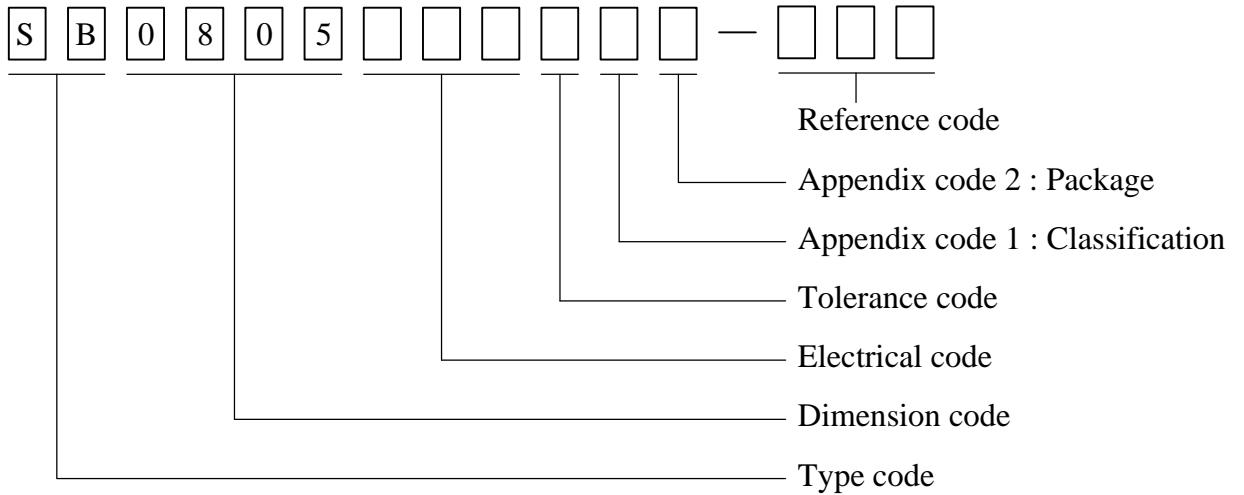
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VI . Drawing number expression :



Appendix code 1 : Product Classification

Appendix code 2 : Package Information

Code	Inner package	Cover tape	Carrier tape	Bag	Package Q'TY	Remark
B	T/R (Reel package)	UCT	Antistatic	Antistatic	800 pcs	

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VII . Reliability test :

Item	Reference documents	Test Condition	Test Specification
1.High Temperature Exposure	MIL-STD-202 Method 108	1.Temperature: 125±2℃ 2.Time:96±2 hours.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
2.Temperature Cycling	JESD22-A 104	1.Temperature: -40℃ ~ +125℃ 2.Number of cycle:100 cycles. 3.Dwell time:30 minutes	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
3.Biased Humidity Test	MIL-STD-202 Method 103	1.Temperature : 85±2℃ 2.Humidity: 85% RH. 3.Time:96±2 Hours	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
4.Operational Life	JESD22-A 108	1.Temperature: 125℃ (Temp. rise included) 2.Time:96±2 hours. 3.Rated current	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
5.External Visual	JESD22-B 101 & MIL-STD-883 Method 2009	Inspect product constructions, marking and workmanship.	1.No pollution on the surface of products. 2.Clear marking. 3.No crack.
6.Physical Dimensions	JESD22-B 100	Verify physical dimensions to the applicable product detail specification.	Per product specification standard
7.Resistance to solvents	MIL-STD-202 Method 215	Immerse into solvent for 3±0.5 minutes & brush 10 times for 3 cycles.	1.No body change in apperance. 2.No marking blurred. 3.Inductance shall not change more than ±10%.
8.Vibration Test	MIL-STD-202 Method 204	1.Frequency and Amplitud : 10-2000-10 Hz, 1.5 mm. 2.Direction:X, Y, Z 3.Test duration:2 hours for each direction, 6 hours in total.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
9.Resistance To Soldering Heat Test	MIL-STD-202 Method 210 & J-STD020D.1	1.Highest temperature : 245±5℃ 2.Time (temp. ≥ 217℃) : 60~150 Seconds. 3.IR reflow times : 3 times.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
10.Saturation Current	JIS C 6436 & User SPEC.	1.Applied rated current for 5 seconds. 2.Saturation current	Inductance shall not drop more than 10% typ.
11.Over load	JIS C 6436 & User SPEC.	1.Applied one and half rated current for a period of 5 minutes. 2.Rated current	No electrical or mechanical damage
12.Temperature Rise Current	JIS C 6436 & User SPEC.	1.Applied rated current for 10 minutes. 2.Temperature measure by digital surface thermometer. 3.Irms current	Surface temperature rise is less than 40℃ max.
13.Solderability Test	J-STD-002 & JESD22-B 102	1.Baking in pre-testing : 150±5℃ / 16Hours±30 min. 2.Peak temperature : 240±5℃ 3.Time (temp. ≥ 217℃) : 60~150 seconds. 4.IR reflow times : 1 times.	More than 95% soldering coverage min on terminations.
14.Electrical Characteriazation	MIL-STD-202 Method 304 & User SPEC.	1.Operating temperature : -40℃~125℃ 2.Room temperature : 25℃.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
15.Drop	CNS-C6354 & GB/T 2423.8	1.Products shall be mounted on SPEC. pcb and dropped down from a heigh of 1m 2.Drop total time : 6 time (Every side ofsample drop 2 times)	1. Adhesion on PCB shall be enough. 2. Product appearance shall not break. 3. No electrical damage.
16.Terminal Strength Test	IEC 60068-2-21	1.Apply push force to samples mounted on PCB. 2.Force of 1.8 kg for 60±1 seconds.	After test, inductors shall be no mechanical damage.

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